IPC ASSOCIATION ELECTRONIC	Material Com © Copyright 2005. international and P	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
1752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute								ials and M	als and Mfg Information			
Supplier	r Information													
Company name*			Company unique ID			ī	Unique ID Authority				Response Date*			
onsemi										2025-06-02				
Contact N	ame	Title - Contact				Phone - Contact*				Email - Contact*				
Product-I	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Authorize	d Representative*	Title - Representative			1	Phone - Representative*				Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
	Requester Item Number Mfr Item		Number Mfr Item Name				Effective Da	ate Ver	rsion	on Manufacturing Site		Weight*	UOM	Unit Type
		NVMFS5C404NLT3G T6-40V N 0.67 mG		Ohms LL		2025-06-02 MY		MY1	10		mg	Each		
Manufa	cturing Process Inform	ation									·			
	Terminal Plating / Grid Array Material			Terminal Base Alloy J-STD-020 MS		SL Rating	<u> </u>		dy Temperati	nture Max Time at Peak Temper		ure Nun	nber of Reflow Cyc	les
Matte Tin (Sn) - annealed CU Alloy			1			260		C	30	secon	ds 3			
Comments	<u> </u>													
evel 1 - m	aximum time at peak tempera	ture during sol	dering is 10-3	0 seconds										
or more	information regarding materia	l composition	please refer to	page 3										

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.										
RoHS Declaration * 4 - Item(s	) does not contain RoHS restricted substance	es per the definition above except for selected exemp	otions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-6_								

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

<b>Homogeneous Material</b>	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	4.8	mg	Supplier	Iron (Fe)	7439-89-6		0.0048	mg
			Supplier	Copper (Cu)	7440-50-8		4.7938	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0014	mg
Die	0.61	mg	Supplier	Silicon (Si)	7440-21-3		0.61	mg
Die Attach Solder	1.99	mg	Supplier	Silver (Ag)	7440-22-4		0.0498	mg
			A	Lead (Pb)	7439-92-1	7a	1.8407	mg
			Supplier	Tin (Sn)	7440-31-5		0.0995	mg
Lead Frame	47.6	mg	Supplier	Silver (Ag)	7440-22-4		0.0286	mg
			Supplier	Iron (Fe)	7439-89-6		0.0476	mg
			Supplier	Copper (Cu)	7440-50-8		47.5096	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0143	mg
Mold Compound-Black	49.2	mg		Epoxy resin	proprietary data		3.69	mg
			Supplier	Phenolic Resin	Proprietary Data		1.23	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		3.69	mg
			Supplier	Carbon Black (C)	1333-86-4		0.246	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		40.344	mg
Plating	1.7	mg	Supplier	Tin (Sn)	7440-31-5		1.7	mg
Wire Bond - Cu	0.05	mg	Supplier	Copper (Cu)	7440-50-8		0.05	mg